



PS7241E-1B

4-PIN SOP 400 V BREAK DOWN VOLTAGE NORMALLY CLOSE TYPE 1-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7241E-1B is an optically coupled element that combines a GaAs infrared LED on the input side with a normally close MOS FET on the output side to realize an excellent cost performance.

The small, thin package and high sensitivity of this element makes it ideal for battery-driven mobile devices, and its small offset voltage at power-on and good linearity also make it suitable for controlling micro analog signals.

FEATURES

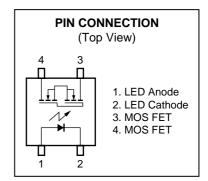
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- 1 channel type (1 b output)
- Low LED operating current (IF = 3 mA)
- · Designed for AC/DC switching line changer
- · Low offset voltage
- Ordering number of taping product: PS7241E-1B-E3, E4, F3, F4
- · Pb-Free product
- Safety standards

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- UL approved: File No. E72422
- BSI approved: File No. 8241/8242

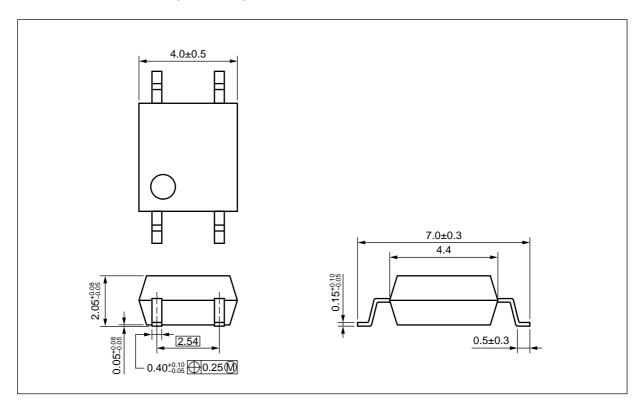
APPLICATIONS

- · Laptop PC, PDA
- Modem card
- Telephone, FAX
- · Measurement equipment

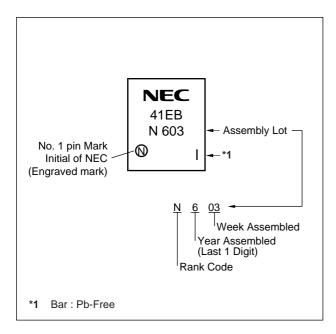


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PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7241E-1B	PS7241E-1B-A	Pb-Free	Magazine case 100 pcs	Standard products	PS7241E-1B
PS7241E-1B-E3	PS7241E-1B-E3-A		Embossed Tape 900 pcs/reel	(UL, BSI approved)	
PS7241E-1B-E4	PS7241E-1B-E4-A				
PS7241E-1B-F3	PS7241E-1B-F3-A		Embossed Tape 3 500 pcs/reel		
PS7241E-1B-F4	PS7241E-1B-F4-A				

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	PD	50	mW
	Peak Forward Current *1	I FP	1	Α
MOS FET	Break Down Voltage	VL	400	V
	Continuous Load Current	lι	120	mA
	Pulse Load Current ² (AC/DC Connection)	ILP	240	mA
	Power Dissipation	Po	300	mW
Isolation Voltage ^{*3}		BV	1 500	Vr.m.s.
Total Power Dissipation		Рт	350	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		T _{stg}	-40 to +100	°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at $T_A = 25^{\circ}C$, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

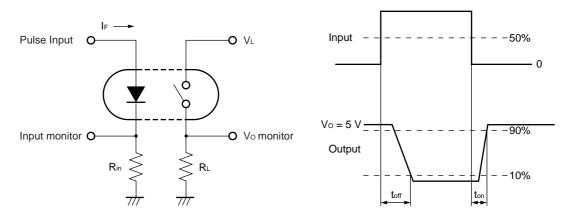
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	3	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

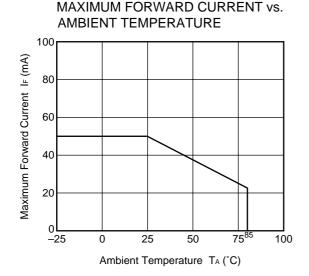
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lR	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	Loff	IF = 10 mA, VD = 400 V		0.03	1.0	μА
	Output Capacitance	Cout	IF = 10 mA, VD = 0 V, f = 1 MHz		206		pF
Coupled	LED Off-state Current	I Foff	I∟ = 120 mA			3.0	mA
	On-state Resistance	Ron1	IF = 0 mA, IL = 10 mA		22	35	Ω
		Ron2	$I_F = 0 \text{ mA}, I_L = 120 \text{ mA}, t \le 10 \text{ ms}$		17	24	
	Turn-on Time*1, 2	ton	If = 10 mA, Vo = 5 V, RL = 500 Ω ,		0.07	0.2	ms
	Turn-off Time*1, 2	toff	PW ≥ 10 ms		1.0	3.0	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.5		pF

*1 Test Circuit for Switching Time

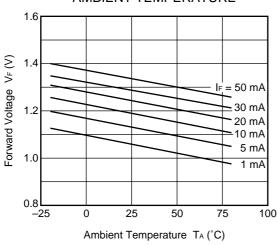


Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

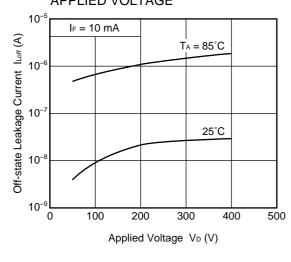
<R> TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)



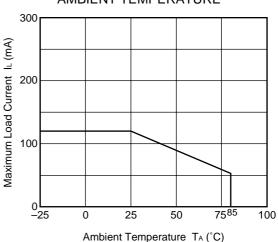




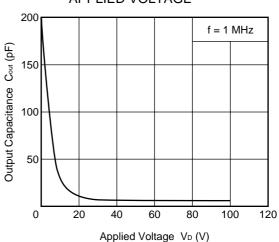
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



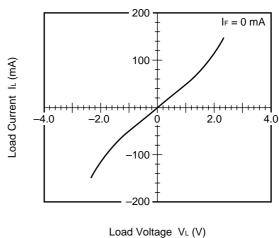
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

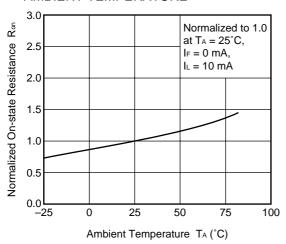


LOAD CURRENT vs. LOAD VOLTAGE

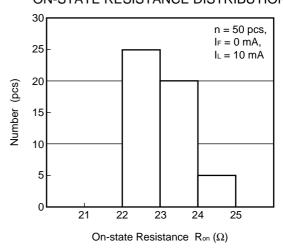


Remark The graphs indicate nominal characteristics.

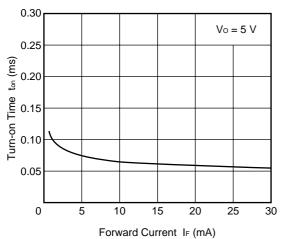
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



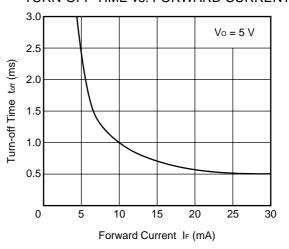
ON-STATE RESISTANCE DISTRIBUTION



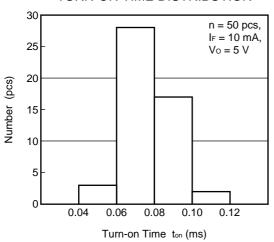
TURN-ON TIME vs. FORWARD CURRENT



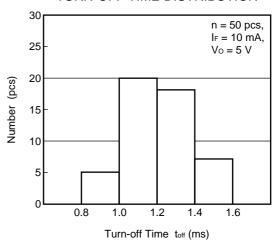
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

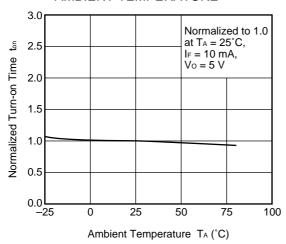


TURN-OFF TIME DISTRIBUTION



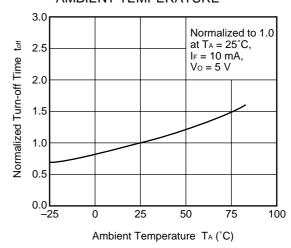
Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

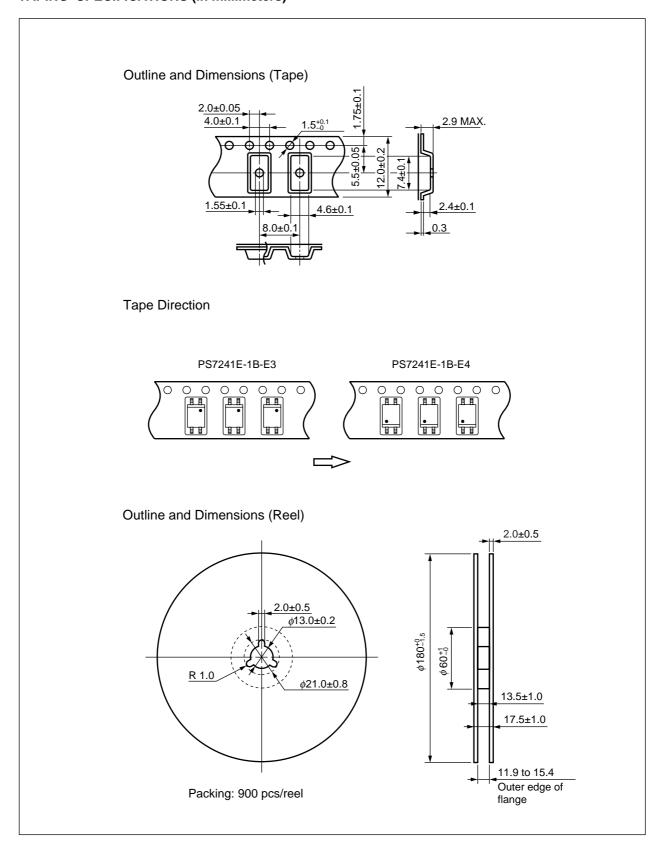


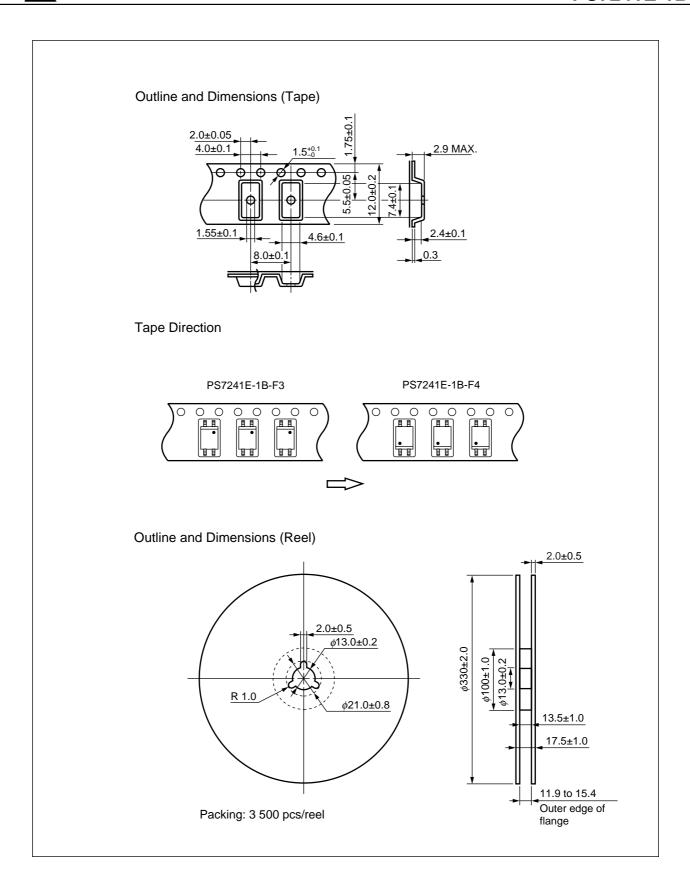
Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



TAPING SPECIFICATIONS (in millimeters)





RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

· Peak reflow temperature 260°C or below (package surface temperature)

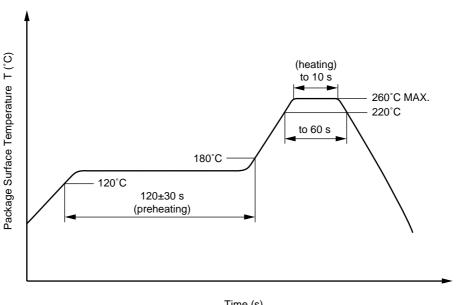
• Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220°C 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

 Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

· Preheating conditions 120°C or below (package surface temperature)

 Number of times One

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

• Peak temperature (lead part temperature) 350°C or below • Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
 - 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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Subject: Compliance with EU Directives

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CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)		on contained devices	
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

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